

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC4225IGN-2#TRPBF

(Engineering Calculation)

SSOP

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TOTAL MASS (g): 0.147107

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000292	1000000	35362.1123812		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.058949	975000	400723.03125		
		Iron (Fe)	7439-89-6	0.001451	24000	9863.59667969		
		Phosphorus (P)	7723-14-0	0.000018	300	122.36026001		
		Zinc (Zn)	7440-66-6	0.000042	700	285.507203184		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-99-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.060460</b>	<b>1000000</b>	<b>410994.53125</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.003400	1000000	23109.7734375		
<b>External Plating Total:</b>						<b>0.003400</b>	<b>1000000</b>	<b>23109.7734375</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.000484	1000000	3290.13110352		
<b>Internal Plating Total:</b>						<b>0.000484</b>	<b>1000000</b>	<b>3290.13110352</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001346	750000	9149.828125		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000449	250000	3052.20874023		
		<b>Die Attach Total:</b>				<b>0.001795</b>	<b>1000000</b>	<b>12302.0371094</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.007726	103000	52519.7421875
Bromine (Br)	40093-93-8			0.000000	0	0		
Silica (SiO2)	60676-86-0			0.067134	895000	456362.96875		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000150	2000	1019.66888428		
<b>Encapsulation Total:</b>						<b>0.075010</b>	<b>1000000</b>	<b>509902.40625</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000756	1000000	5129.13085938		

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